

ETERTEC® LAMINAR® PHOTORESIST

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
ETERTEC HP-3400	10 15 20 24 38	<ul style="list-style-type: none"> * Excellent adhesion and excellent chemical resistance to etching * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Applicable for flexible printed-circuits boards fabrication * Good contrast * Low developing foaming and sludge 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch Lead Frame Chemical Milling and PKG application</p>
ETERTEC HQ-6000	33 40 50	<ul style="list-style-type: none"> *High throughput *Excellent plating behavior characteristic *High resolution *Easily stripping with small flake size *Broad processing latitude in each process step *Good contrast after exposure for easy inspection *Ammonic and acid etching resistance *Good tenting behavior characteristic 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch</p>
ETERTEC HQ-6300	38 47	<ul style="list-style-type: none"> *High throughput *Excellent plating behavior characteristic *Excellent resistance for Ni/Au plating *High resolution *Good tenting behavior characteristic *Easily stripping with small flake size *Broad processing latitude in each process step *Good contrast after exposure for easy inspection *Ammonic and acid etching resistance 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch</p>

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
ETERTEC HT-100	40 50	<ul style="list-style-type: none"> * Excellent resistance to all acid plating * High resolution * Reliable tenting up to 0.300 inches * Easily stripping and filterable * Broad processing latitude in each process step * Good contrast after exposure for easy inspection 	<p style="text-align: center;">Plating Print-and-etch Tent-and-Etch</p>
ETERTEC HT-300	25 30	<ul style="list-style-type: none"> * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * High throughput * Broad processing latitude in each process step * Excellent conformability to the substrate * Easily stripping and filterable * Applicable for flexible printed circuits boards fabrication 	<p style="text-align: center;">Print-and-Etch</p>
ETERTEC HT-700	25 30	<ul style="list-style-type: none"> * Excellent adhesion and excellent chemical resistance to acidic etching * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Excellent conformability to the substrate * Fast photospeed * Applicable for flexible printed-circuits boards fabrication 	<p style="text-align: center;">Print-and-Etch</p>

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
ETERTEC HT-700M	24 29	<ul style="list-style-type: none"> * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Excellent conformability to the substrate * Fast photospeed * Applicable for flexible printed-circuits boards fabrication * Good contrast * Low developing foaming and sludge 	Print-and-Etch
ETERTEC HT-100T	30 40 50	<ul style="list-style-type: none"> * Suitable for tent-and-etch applications with acid etching. * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * High throughput * Broad processing latitude in each process step * Excellent conformability to the substrate * Easily stripping and filterable * Applicable for flexible printed circuits boards fabrication 	Plating Tent-and-Etch Print-and-Etch
ETERTEC HT-200T	24 29 38 49	<ul style="list-style-type: none"> * High throughput * Excellent plating behavior characteristic * Excellent adhesion and resolution * Good tenting behavior characteristic * Easily stripping with small flake size * Broad processing latitude in each process step * Good contrast after exposure for easy inspection 	Plating Print-and-Etch Tent-and-Etch

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
ETERTEC HT-1900	29 38 49	<ul style="list-style-type: none"> * Suitable for tent-and-etch applications with acid etching. * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * High throughput * Broad processing latitude in each process step * Excellent conformability to the substrate * Easily stripping and filterable * Applicable for flexible printed circuits boards fabrication 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch</p>
LAMINAR E7600	30 40 50	<ul style="list-style-type: none"> * Suitable for tent-and-etch applications with acid etching. * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * High throughput * Broad processing latitude in each process step * Excellent conformability to the substrate * Easily stripping and filterable * Applicable for flexible printed circuits boards fabrication 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch</p>
LAMINAR E7800	29 38 49 63 75 100	<ul style="list-style-type: none"> * High throughput * Excellent plating behavior characteristic * High resolution * Good tenting behavior characteristic * Easily stripping with small flake size * Broad processing latitude in each process step * Good contrast after exposure for easy inspection * Good resistance to ammoniac and acid etch * Excellent resistance to Ni/Au plating 	<p style="text-align: center;">Plating Tent-and-Etch Print-and-Etch</p>

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
LAMINAR E9000	29	<ul style="list-style-type: none"> * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Excellent conformability to the substrate * Fast photospeed * Applicable for flexible printed-circuits boards fabrication * Good contrast * Low developing foaming and sludge 	Print-and-Etch
LAMINAR E9100	29	<ul style="list-style-type: none"> *High throughput *High resolution *Easily stripping with small flake size *Broad processing latitude in each process step *Good contrast after exposure for easy inspection *Excellent ammoniac and acid etching resistance 	Print-and-Etch
LAMINAR E9200	33 40 50 62 75	<ul style="list-style-type: none"> *High throughput *Excellent plating behavior characteristic *High resolution *Easily stripping with small flake size *Broad processing latitude in each process step *Good contrast after exposure for easy inspection *Ammoniac and acid etching resistance *Good tenting behavior characteristic 	Plating Tent-and-Etch Print-and-Etch

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
LAMINAR E9300	29 38 49	<ul style="list-style-type: none"> *Suitable for tent-and-etch applications with acid etching. * Excellent adhesion and excellent chemical resistance to etch * Excellent resolution * High throughput * Broad processing latitude in each process step * Excellent conformability to the substrate * Easily stripping and filterable * Applicable for flexible printed circuits boards fabrication 	Plating Tent-and-Etch Print-and-Etch
ETERTEC HQ-6200	49	<ul style="list-style-type: none"> *Excellent adhesion *Excellent resolution * Easily stripping and filterable *Broad processing latitude in each process step *Excellent conformability to the substrate *Applicable for ENIG process 	Plating Tent-and-Etch Print-and-Etch ENIG
LAMINAR GA	75 101	<ul style="list-style-type: none"> *Excellent fine line reproduction *Surface conformity *High productivity *Wet and dry lamination *Excellent yields *Broad process latitude 	Plating Print-and-Etch
LAMINAR UD700	30 40 50 62	<ul style="list-style-type: none"> *Good adhesion *Fast photo-speed high resolution capability *Straight side-walls *Clean developing *In-line process capability and high chemical resistance 	Plating Print -and-Etch LDI application
LAMINAR UD1000	30 40 50 62	<ul style="list-style-type: none"> *Good adhesion *Fast photo-speed high resolution capability *Straight side-walls *Clean developing *In-line process capability and high chemical resistance 	Plating Print -and-Etch LDI application

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
ETERTEC LR-5201		<ul style="list-style-type: none"> * Applicable to horizontal roller coating machine * Excellent adhesion and excellent chemical resistance to alkaline etching solution * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Excellent conformability to the substrate * Fast photospeed 	Print-and-Etch
ETERTEC LR-5206		<ul style="list-style-type: none"> * Applicable to vertical roller coating machine * Excellent adhesion and excellent chemical resistance to alkaline etching solution * Excellent resolution * Easily stripping and filterable * Broad processing latitude in each process step * Excellent conformability to the substrate * Fast photospeed 	Print-and-Etch
CONFORMASK 2500	38 58	<ul style="list-style-type: none"> * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL- 94V0 * Conformability * Five layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry
CONFORMASK 3300	25 38	<ul style="list-style-type: none"> * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL- 94V0 * Conformability * Five layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
CONFORMASK 2000	38 58	<ul style="list-style-type: none"> * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL- 94V0 * Conformability * Five layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry
DYNAMASK KM	76 101	<ul style="list-style-type: none"> * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL-94V0 * Three layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry
DYNAMASK 5000	40 76 101	<ul style="list-style-type: none"> * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL-94V0 * Three layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry
DYNAMASK 5200	38 58	<ul style="list-style-type: none"> * Halogen free * Excellent resolution * High gloss * Low odor * Fast exposure * Scratch resistance * Low light bleed * UL-94V0 * Three layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry

Type		Performance Features	Suggested Uses
Grade	Available thickness (µm)		
DYNAMASK 6000	38 58	<ul style="list-style-type: none"> * Excellent resolution * Low odor * Fast exposure * Scratch resistance * UL-94V0 * Three layer structure 	Permanent solder mask on rigid PWB using either epoxy or polyimide laminates and copper or tin/lead circuitry